

# Preliminary Agenda 21 January 2010

## – PRELIMINARY MEETING AGENDA – CE-2.0 COMMITTEE ON CONNECTOR AND SOCKET STANDARDS MEETING NO. 46

Hyatt Regency Grand Cypress  
1 Grand Cypress Blvd  
Orlando, FL 32836  
For reservations call: 1-888-421-1442

The CE-2.0 Committee on Connector Standards and its Subcommittees, Working Groups, and Special Task Groups will meet on 27 – 28 April 2010 (2 day meeting). The meeting will start at 9:00 AM on **Tuesday 27 April 2010** and conclude at 4:30 PM on **Wednesday 28 April 2010**.

**Note: The meeting will run sequentially, with no specific time scheduled for the individual agenda items shown below. The Chairman may vary the sequence as needed. Members are requested to plan on attending the meeting for a full two days (early departures effect the completion of agenda work).**

**If any SP receives insufficient votes for approval, the committee may approve the document for EDEC ballot at this meeting. It is the responsibility of the member to submit comments in writing prior to the meeting.**

1. Approval of the 13 – 14 October 2009 minutes

2. CHAIRMAN'S REPORT AND ANNOUNCEMENTS (Frank Ruffino, Chairman)

3. SUBCOMMITTEE MEETINGS

A. CE-2.1 Test Procedures (Chairman: Carl Fritz, Vice Chairman, Max Peel)

B. CE-2.3 Contact Specifications (was subcommittee CE-2.6) (Chairman: Dave Bouzek)

C. CE-2.4 Editing Subcommittee (was subcommittee CE-2.7) (Chairman: Carl Fritz)

D. CE-2.5 International Standards Subcommittee (was subcommittee CE-2.8) (Chairman: Jeff Toran)

4. CONNECTOR AND SOCKET DETAIL SPECIFICATIONS

A. SP-4970, EIA-540DAAA-A, Detail, DIP

This will be reissued as a new ballot.

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## **B. SP-4971, EIA-700A0AB, 68-pin Memory Card Connector**

This will be reissued as a new ballot.

## **C. SP-5112 as follows:**

- EIA-700A0AC: Detail, 88-pin DRAM Connector
- EIA-540A000-A: Sectional, Chip Carrier Sockets
- EIA-540AA00: Blank, Leadless Chip Carrier Sockets
- EIA-540AAAA: Detail, Type A Chip Carrier Sockets
- EIA-540AB00: Blank, PQFP
- EIA-540ABAA: Detail, PQFP
- EIA-540AC00: Blank, PCC
- EIA-540ACAA: Detail, PCC
- EIA-540AD00: Blank, Adaptor QFP to PGA
- EIA-540B000: Sectional, PGA
- EIA-540BA00: Blank, PGA
- EIA-540BAAB: Detail, Non-Mechanical PGA
- EIA-540BAAC: Detail, Flex Carrier PGA
- EIA-540D000-A: Sectional, In-Line Packages
- EIA-540DA00: Blank, DIP (Will be sent out for review)
- EIA-540DAAB: Detail, Flex Carrier DIP
- EIA-540EA00: Blank, Round Sockets
- EIA-540EAAA: Detail, Round Sockets
- EIA-540F000: Sectional, Multi-Package Modules

This will be reissued as a new ballot.

## **D. New Specification for Mini-Change A-Size (2-6 pole) Connector (Frank Ruffino)**

Frank reported that work is on going.

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## E. Connector and Socket Specification Status

Carl Fritz gave a presentation on the status of all connector and socket specification that he extracted from the EIA database that appear to be the responsibility of CE-2.0. He will coordinate review of the accuracy with EIA. The following tables reflect his findings.

**Connector Specifications Past Due for 5-Year Review**

EIA	Rev	Title	Date of last issue	5 Year due date	Years past due
270		Tools, Crimping, Solderless Wiring Devices - Recommended Procedures for User Certification	January-62	December-66	42
297	A	Cable Connectors for Audio Facilities for Radio Broadcasting-Correction Sheet	June-70	May-75	34
406		General Document for Connectors, Electric, Printed-Wiring Board-IPC-C-405A	January-74	December-78	30
429		Connectors, Electrical Flat Cable Type-IPC FC-218B	January-76	December-80	28
380	A	Electrical Connectors, Small Contact Standard for	January-78	December-82	26
IS-47		Contact Termination Finish Standard for Surface Mount Devices	July-87	June-92	17
IS-84		Interim Detail Specification for 2.5 mm Two Part Connector for Use in Electronic Equipment	April-92	April-97	12
280	C	Solderless Wrapped Electrical Connections	May-92	May-97	12
700A0AA		Detail Specification for 1.27 mm Pitch, Ribbon Contact, Trapezoidal Shaped, Shielded I/O Connector	April-96	April-01	8
700AAAB	A	Detail Specification for 1.0 mm, Two-Part Connectors for Use with Parallel Printed Boards	January-96	December-00	8
700C000		Sectional Specification for Circular Multicontact Connectors of Assessed Quality (for Frequencies Essentially Below 3 MHz)	January-97	January-02	7
7000000	A	Generic Specification for Electronic and Electrical Connectors of Certified Quality (for Frequencies Essentially Below 3 MHz)	August-96	July-01	7
IS-753		Two-Part High Density Blade and Backplane Tuning Fork Connector	February-98	February-03	6
700A0AD		Detail Specification for the Interface of the 1.27 mm Pitch, Ribbon Contact (Leaf Spring), Trapezoidal Shaped, Self-Locking I/O Connector	November-97	October-02	6
700D000		Sectional Specification for Discrete Contacts of Certified Quality (for Use in dc/Low Frequency Analog Applications and in Digital Applications Employing High Speed Data Rates)	January-98	January-03	6
710		Requirements Guide for Space Grade Electrical Connectors	October-97	October-02	6

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## Connector Specifications Past Due for 5-Year Review

EIA	Rev	Title	Date of last issue	5 Year due date	Years past due
700B000		Sectional Specification for Rectangular/Trapezoidal Connectors of Certified Quality	May-99	May-04	5
700BA00		Blank Detail Specification for Rectangular/Trapezoidal Connectors of Certified Quality	September-98	September-03	5
700A0AE		Detail Specification for Trapezoidal Connectors with Nonremovable Ribbon Cable Contacts on 1.27mm Pitch Double Row Used with Single Connector Attachments (SCA2)	January-00	December-04	4
700A0AF		Detail Specification for Trapezoidal Shielded Connector 0.8 mm Pitch Used with Very High Density Cable Interconnect (VHDCI)	July-00	June-05	4
700BAAD		Detail Specification for Shielded Rectangular Connectors for Universal Serial Bus Plus Power Connectors Series "A"	May-00	April-05	4
700BAAE		Detail Specification for Shielded Rectangular Connectors for Universal Serial Bus Plus Power Connectors Series "B"	May-00	April-05	4
616	A	Detail Specification for 2 Millimeter, Two-Part Connectors for Use with Printed Boards and Backplanes	November-02	November-07	1
622	A	Glossary of Electrical Connector Related Terms	August-07	August-12	-4
700A0AC		DETAIL SPECIFICATION FOR 1.00 MM PITCH, 88 CIRCUIT DRAM MEMORY CARD INTERCONNECT SYSTEM	August-96	Ausust-01	

- Approved to be obsoleted or rescinded

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## Socket Specifications Past Due for 5-Year Review

EIA	Rev	Title	Date of last issue	5 Year due date	Years past due
CB-5-1		Recommended Test Procedure for Semiconductor Thermal Dissipating Devices-Addendum to CB5	May-71	April-76	33
540ADAA		Detail Specification for Adaptor-Carrier Quad Flatpack to Pin Grid Array Sockets for Use in Electronic Equipment	February-92	January-97	12
540FA00	A	Blank Detail Specification for Multi-Package Module Sockets for Use in Electronic Equipment	April-92	March-97	12
540FAAA		Detail Specification for Multi-Package 100 Mil Pitch, Vertical Mounting Format Module Sockets for Use in Electronic Equipment	January-92	December-96	12
540FAAB		Detail Specification for Multi-Package 100 Mil Pitch, Angled Mounting Format Module Sockets for Use in Electronic Equipment	January-92	December-96	12
540FAAC		Detail Specification for Multi-Package 50 Mil Pitch, Vertical Mounting Format Module Sockets for Use in Electronic Equipment	January-92	December-96	12
540FAAD		Detail Specification for Multi-Package 50 Mil Pitch, Angled Mounting Format Module Sockets for Use in Electronic Equipment	January-92	December-96	12
540DB00		Blank Detail Specification for Decoupling Capacitor Dual In-Line Package Sockets	June-93	December-97	11
540DB00	I	BLANK DETAIL SPEC FOR DIP SOCKETS W/DECOUPLING CAP	June-93	June-98	11
540E000		Sectional Specification for Round-Style Sockets for Use in Electronic Equipment	February-93	February-98	11
540G000		Sectional Specification for Burn-In Sockets for Use in Electronic Equipment	January-93	December-97	11
540GA00		Blank Detail Specification for Burn-In Sockets for Chip Carrier Packages with Molded Carrier Rings for Use in Electronic Equipment	January-93	December-97	11
540GAAA		Detail Specification for Burn-In Sockets for Chip Carrier Packages with Molded Carrier Rings for Use in Electronic Equipment	January-93	December-97	11
540DBAA		Detail Specification for Decoupling Capacitor Dual In-Line Package Sockets for Use in Electronic Equipment	January-94	December-98	10
675		Specification for Small Form Factor 33.0 mm (1.3 in) Disk Drives	January-96	December-00	8
540BAAA	A	Detail Specification for Mechanically Actuated (Zero and Low Insertion Force) Sockets for Pin Grid Array Devices with 2.54 mm X 2.54 mm (0.1 in X 0.1 in) Spacing for Use in Electronic Equipment	August-96	August-01	7
677		Specification for Small Form Factor Power Connector Pin Dimensions	June-97	June-02	7
IS-701		Production Ball Grid Array (BGA) Socket Test Specification	July-96	July-01	7

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## Socket Specifications Past Due for 5-Year Review

EIA	Rev	Title	Date of last issue	5 Year due date	Years past due
540CAAC	A	Detail Specification for 2 Pole, 10 A Relay Sockets	November-98	November-03	5
740		Specification for Small Form Factor 88.9 mm (3.5 in) Disk Drives	July-99	June-04	5
540CAAD	A	Detail Specification for 2 Pole, 5 A Relay Sockets	August-99	August-04	4
540CAAE	A	Detail Specification for 3 Pole, 10 A Relay Sockets	August-99	August-04	4
540HA00		Blank Detail Specification for Burn-In Sockets Used with Ball Grid Array Devices for Use in Electronic Equipment	May-00	April-05	4
540HAAA		Detail Specification for Burn-In Sockets Used with Ball Grid Array Devices for Use in Electronic Equipment	June-00	May-05	4
540J000		Sectional Specification for Battery Holders for Use in Electronic Equipment	May-00	April-05	4
540J0AA		Detail Specification for Cylindrical Battery Holders, Standard Profile, for Use in Electronic Equipment	May-00	April-05	4
773		Check List for Document Development and Revision	May-00	April-05	4
540J0AB		Detail Specification for Coin Cell Battery Holders for Use in Electronic Equipment	June-01	May-06	3
741		Specification for Small Form Factor 133.35 mm (5.25 in) Disk Drives	May-01	April-06	3
540B0AA	A	Detail Specification for Production Ball Grid Array (BGA) High Pin Count (1089 Pins and Greater) Socket for Use in Electronic Equipment-Revision	October-01	September-06	2
676	A	Specification for Parallel 1.8 inch Drive Form Factor (78 millimeter x 54 millimeter)	June-06	June-11	-2
674	A	Specification for Dimensions and Connectors Locations of Small Form Factor 45 millimeter (1.8 inch) Disk Drive	August-06	August-11	-3

- Approved to be obsoleted or rescinded
- Duplicate listing

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## Unknown Connector Documents

EIA	Rev	Title	Date of last issue	5 Year due date	Years past due	Comments
51		EMISSION LIMITATION AM BROADCAST TRANSMISSION	September-88	August-93		Number unidentifiable
5810000		GENERIC SPEC RECTANGULAR CONNECTOR FOR FREQUENCIES BELOW 3 MHZ				Number unidentifiable
5880000		GEN SPEC PRINTED BD CONNECTORS OF ASSESSED QUALITY				Number unidentifiable
437-1		ADDENDUM NO. 1 TO EIA-437 BASIC SENSITIVE SWITCHES	September-78	August-83		Number unidentifiable
437-2			May-78	April-83		RESCINDED 9/25/89
437-3			September-78	August-83		RESCINDED 9/25/89
437-4			September-89	August-94		RESCINDED 9/25/89
437-5		20 AMP DOUBLE BREAK SENSITIVE SWITCHES	March-81	February-86		Number unidentifiable
437-6		15 AMP DOUBLE BREAK SENSITIVE SWITCHES	March-81	February-86		Number unidentifiable
437-7		10 AMP DOUBLE SENSITIVE SWITCHES	June-80	May-85		Number unidentifiable
437-8		8 AMP DOUBLE SENSITIVE SWITCHES	June-80	June-85		Number unidentifiable
64		INTERIM STD, 2MM TWO-PART CONN FOR PRINT WIRING BD	March-91	March-96		Number unidentifiable
700A000		SECT SPEC FOR PRINTED BOARD CONNECTORS ESSENTIALLY BELOW 3MHZ				No record that specification was ever issued
700A0AG		DT SP TRAPEZOIDAL PIN-AND-SOCKET CONN FIBER CHANNEL APPLICATIONS				No record that specification was ever issued
700AAAA		DT SP 1.27 mm PITCH RIBBON CONTACT TRAPEZOIDAL SHIELDED I/O CONNC				No record that specification was ever issued
700BAAA		CONNECTOR ELECT RECTANGULAR SCOOP-PROOF LOW FORCE SUBMINIATURE				No record that specification was ever issued
700BAAB		CONNECTORS, ELECTRICAL, RECTANGULAR, BLIND-MATE, SCOOP-PROOF				No record that specification was ever issued
700BAAC		DT SP BLIND-MATE, SCOOP PROOF EVA LOW EARTH ORBIT LEO CONNECTOR				No record that specification was ever issued
700D0AA		HIGH DENSITY TUNING FORK COMPONENTS				No record that specification was ever issued
700DA00		DISCRETE CONTACT BLANK DETAIL SPECIFICATION				No record that specification was ever issued

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## Unknown Socket Documents

EIA	Rev	Title	Date of last issue	5 Year due date	Years past due	Comments
540B0AB		Low Pin Count BGA				Sent letter to EIA to cancel project on 13 May 2008
540D0AA		DET. SPEC - SOCKETS FOR DUAL...PACKAGES	January-90	January-95		No record that specification was ever issued
540F0AG		DETAIL SPEC-SMALL OUTLINE DIMM DUAL-IN-LINE MEMORY MODULE SOCKETS				No record that specification was ever issued
540FAAE		DT SP DUAL IN-LINE MEMORY (DIMM) SOCKETS 1.27 MM VERTICAL MOUNT				No record that specification was ever issued
540FAAF		DT SP 8-BYTE 168 POSITION DUAL IN-LINE MEMORY MODULE SOCKET 1.27				No record that specification was ever issued
540JAAA		DT SP BURN-IN SOCKETS USE W/BALL GRID ARRAY DEVICE USE IN ELEC EQ				No record that specification was ever issued

### F. Obsolete or rescind all Generic, Sectional and Blank Detail Specifications (Carl Fritz)

The unanimously agreed to obsolete all Generic, Sectional and Blank Details Specifications. Carl Fritz has agreed to be project leader. It was moved by Don Chambers and seconded by Frank Ruffino to obtain a project number and send out on SP ballot.

### G. SP-5193, EIA-7000000, EIA-700B000, EIA-700BA00, EIA-700C000, EIA-700D000, EIA-540DB00, EIA-540E000, EIA-540FA00, EIA-540G000, EIA-540GA00, EIA-540HA00 and EIA-540J000 “Electrical Connector and Socket Specifications” (Carl Fritz)

Sent memo (mccwil399) to EIA for EDEC ballot to rescind (withdraw) the listed specifications on 2 December 2009.

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## H. Stabilize Listed Specification

Sent memo (mccwil395) to EIA to obtain a project number to “Stabilize” the following specifications on 28 October 2009:

EIA-	Current Revision	Title
270		Tools, Crimping, Solderless Wiring Devices - Recommended Procedures for User Certification
280	C	Solderless Wrapped Electrical Connections
297	A	Cable Connectors for Audio Facilities for Radio Broadcasting-Correction Sheet
380	A	Electrical Connectors, Small Contact Standard for
406		General Document for Connectors, Electric, Printed-Wiring Board-IPC-C-405A
429		Connectors, Electrical Flat Cable Type-IPC FC-218B
540ADAA		Detail Specification for Adaptor-Carrier Quad Flatpack to Pin Grid Array Sockets for Use in Electronic Equipment
540FAAA		Detail Specification for Multi-Package 100 Mil Pitch, Vertical Mounting Format Module Sockets for Use in Electronic Equipment
540FAAB		Detail Specification for Multi-Package 100 Mil Pitch, Angled Mounting Format Module Sockets for Use in Electronic Equipment
540FAAC		Detail Specification for Multi-Package 50 Mil Pitch, Vertical Mounting Format Module Sockets for Use in Electronic Equipment
540FAAD		Detail Specification for Multi-Package 50 Mil Pitch, Angled Mounting Format Module Sockets for Use in Electronic Equipment
540GAAA		Detail Specification for Burn-In Sockets for Chip Carrier Packages with Molded Carrier Rings for Use in Electronic Equipment
CB-5-1		Recommended Test Procedure for Semiconductor Thermal Dissipating Devices-Addendum to CB5
IS-47		Contact Termination Finish Standard for Surface Mount Devices
IS-84		Interim Detail Specification for 2.5 mm Two Part Connector for Use in Electronic Equipment

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## 5. SFF COMMITTEE PROJECTS

There has been a request received to prepare approximately 22 detail specifications on behalf of the SFF Committee. The committee unanimously agreed to take this on as a project to create new detail specifications. Frank Ruffino has agreed to be project leader. It was moved by Don Chambers and seconded by Kevin Rickard to obtain a project number and send out on letter ballot or SP as determined by the project leader. The motion was unanimously approved.

### 5.1 Active Projects (Frank Ruffino)

#### A. SP or PN-5190, EIA-964, Detail Specification for QSFP+ Copper and Optical Modules (formerly SFF-8436) (Frank Ruffino)

Carl reported that he sent cover memo (mccwil381 and PINS form to EIA requesting a project number on 11 June 2009 on behalf of Frank Ruffino.

Received project numbers 11 June 2009.

#### B. SP or PN-5191, EIA-965, Detail Specification for Mini Multilane Shielded Integrated Connector (formerly SFF-8642) (Frank Ruffino)

Carl reported that he sent cover memo (mccwil381 and PINS form to EIA requesting a project number on 11 June 2009 on behalf of Frank Ruffino.

Received project numbers 11 June 2009.

#### C. SP or PN-5201, EIA-966, Specification for Unshielded Dual Port Serial Attachment Connector (formerly SFF-8482) (Frank Ruffino)

Sent cover memo (mccwil396 and PINS form to EIA requesting a project number on 10 November 2009 on behalf of Frank Ruffino.

Received project numbers 10 November 2009 as follows.

Sent draft to Frank Ruffino on 12 November 2009 to review.

#### D. SP or PN-5202, EIA-967, Specification for Micro Serial Attached SCSI (SAS) Connector (formerly SFF-8486) (Frank Ruffino)

Sent cover memo (mccwil396 and PINS form to EIA requesting a project number on 10 November 2009 on behalf of Frank Ruffino.

Received project numbers 10 November 2009 as follows:.

Sent draft to Frank Ruffino on 12 November 2009 to review.

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## 5.2 Future Projects (Frank Ruffino)

SFF designation	Title	Status
SFF-8079	SFP Rate and Application Selection	
SFF-8087	Mini Multilane Series Connector: Unshielded	
SFF-8088	Mini Multilane Series Connector: Shielded	
SFF-8089	SFP Rate and Application Codes	
SFF-8100	Suite of <2.5" Form Factor Specifications	
SFF-8200	Suite of 2.5" Form Factor Specifications	
SFF-8300	Suite of 3.5" Form Factor Specifications	
SFF-8416	Measurement & Performance Requirements for HPEI Bulk Cable	
SFF-8431	SFP+	
SFF-8432	IPF (Improved Pluggable Formfactor	
SFF-8433	IPF (Improved Pluggable Formfactor) Cage	
SFF-8436	QSFP Copper and Optical Transceivers	<b>(Received project number)</b>
SFF-8448	SAS Sideband Utilization	
SFF-8460	HSS Backplane Design Guidelines	
SFF-8482	Internal Serial Attachment Connector	<b>(Under development)</b>
SFF-8484	4-Wide Internal Serial Attachment Connector	
SFF-8485	Serial GPIO (SGPIO) Bus	
SFF-8486	Micro SAS Connector	<b>(Under development)</b>
SFF-8500	Suite of 5.25" Form Factor Specifications	
SFF-8642	Mini Multilane Series: Shielded Integrated Connector	<b>(Received project number)</b>

## 6. LIASION REPORTS

- A. DSCC, including Army, USAF, Navy; except NAVAIR (Ed Wypasek)
- B. NAVAIR (Dwight Tabit)
- C. SAE (Dave Bouzek)
- D. ASTM (Frank Ruffino)

## 7. OTHER BUSINESS

- A. Review of questionnaire for CE-2.0 (Frank Ruffino)

Activity has been tabled for the time being.

- B. Scope (Frank Ruffino)

Frank presented the revised scope for the ECA web site. Frank will forward to Cecelia.

- D. WEB Database Review (Carl Fritz and Frank Ruffino)

Status update.

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## 8. NEW BUSINESS

## 9. FUTURE MEETINGS

TBD

Respectfully submitted,

Frank Ruffino, Chairman CE-2.0

Prepared by  
Carl Fritz, Secretary CE-2.0